

N-Channel Enhancement Mode Field Effect Transistor

LM5D40N10 use advanced SGT MOSFET technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

Features

Low $R_{DS(on)}$ & FOM

Extremely low switching loss

Excellent stability and uniformity or Invertors

Applications

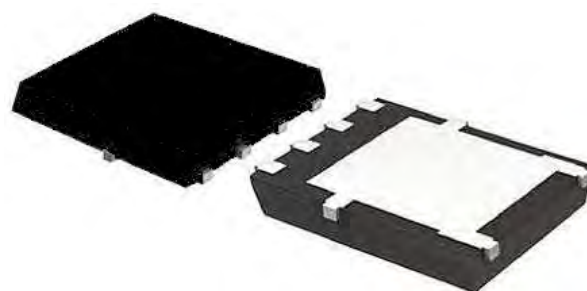
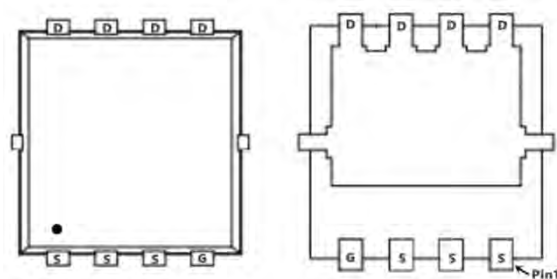
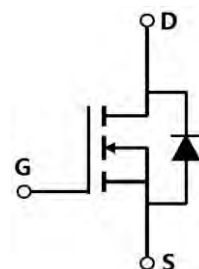
Consumer electronic power supply

Motor control

Synchronous-rectification

Isolated DC

Synchronous-rectification application



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
LM5D40N10	DFN5*6-8L	APG40N10NF	5000

Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_D	40	A
Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{D, \text{ pulse}}$	120	A
Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$	P_D	72	W
Single pulsed avalanche energy ⁵⁾	EAS	30	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^{\circ}\text{C}$
Thermal resistance, junction-case	$R_{\theta JC}$	1.74	$^{\circ}\text{C/W}$

Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	°C/W
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Electrical Characteristics at T_J=25 °C unless otherwise specified

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250 μA	100			V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250 μA	1.0		2.5	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =10 V, I _D =8 A		16	20	mΩ
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =4.5 V, I _D =6 A			26	mΩ
Gate-source leakage current	I _{GSS}	V _{GS} =20 V			100	nA
					-100	
Drain-source leakage current	I _{DSS}	V _{DS} =100 V, V _{GS} =0 V			1	μA
Input capacitance	C _{iss}	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz		1190.6		pF
Output capacitance	C _{oss}			194.6		pF
Reverse transfer capacitance	C _{rss}			4.1		pF
Turn-on delay time	t _{d(on)}	V _{GS} =10 V, V _{DS} =50 V, R _G =2.2 Ω, I _D =10 A		17.8		ns
Rise time	t _r			3.9		ns
Turn-off delay time	t _{d(off)}			33.5		ns
Fall time	t _f			3.2		ns
Total gate charge	Q _g	I _D =8 A, V _{DS} =50 V, V _{GS} =10 V		19.8		nC
Gate-source charge	Q _{gs}			2.4		nC
Gate-drain charge	Q _{gd}			5.3		nC
Gate plateau voltage	V _{plateau}			3.2		V
Diode forward current	I _S	V _{GS} <V _{th}			40	
Pulsed source current	I _{SP}				120	A
Diode forward voltage	V _{SD}	I _S =8 A, V _{GS} =0 V			1.3	V
Reverse recovery time	t _{rr}	I _S =8 A, di/dt=100 A/μs		50.2		ns
Reverse recovery charge	Q _{rr}			95.1		nC
Peak reverse recovery current	I _{rrm}			2.5		A

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, R_G=25 Ω, L=0.3 mH, starting T_J=25 °C.

Electrical Characteristics Diagrams

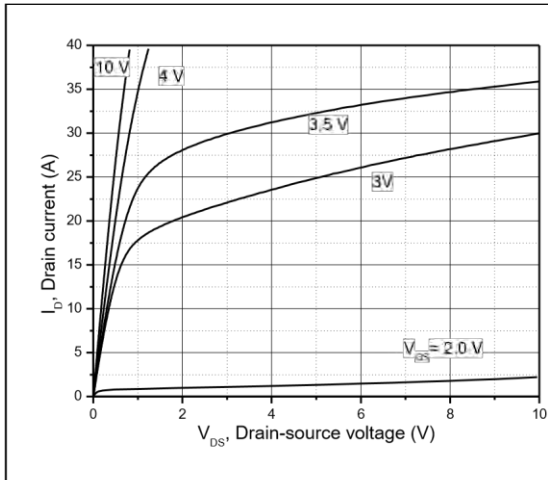


Figure 1, Typ. output characteristics

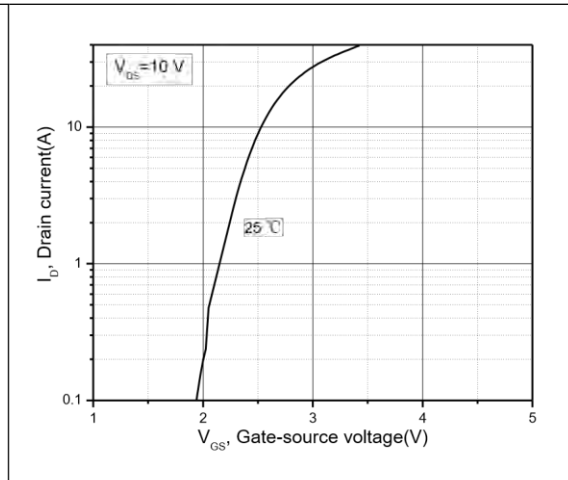


Figure 2, Typ. transfer characteristics

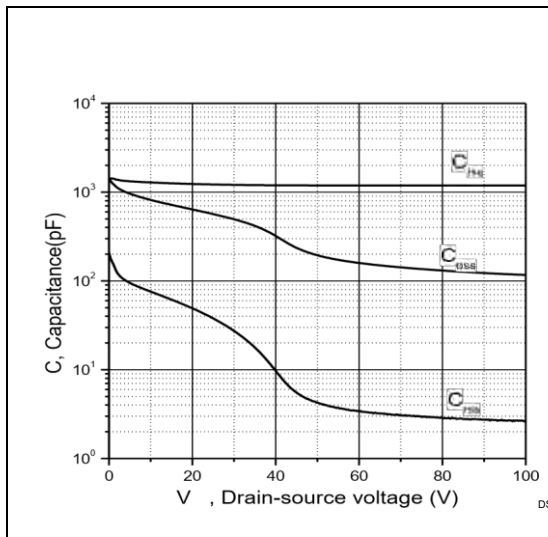


Figure 3, Typ. capacitances

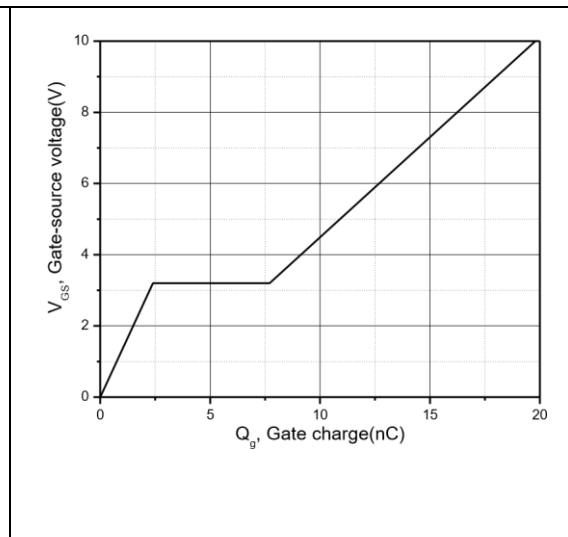


Figure 4, Typ. gate charge

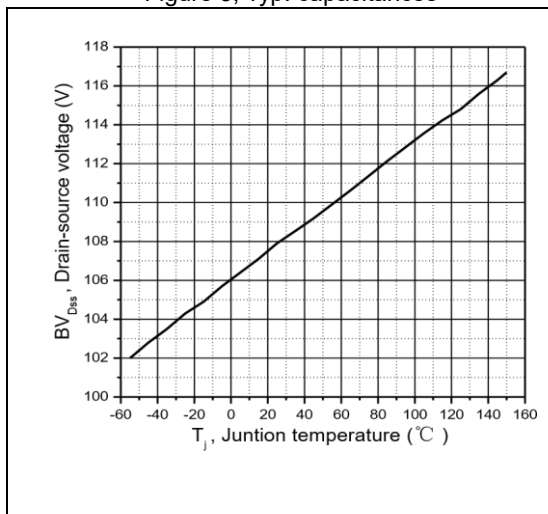


Figure 5, Drain-source breakdown voltage

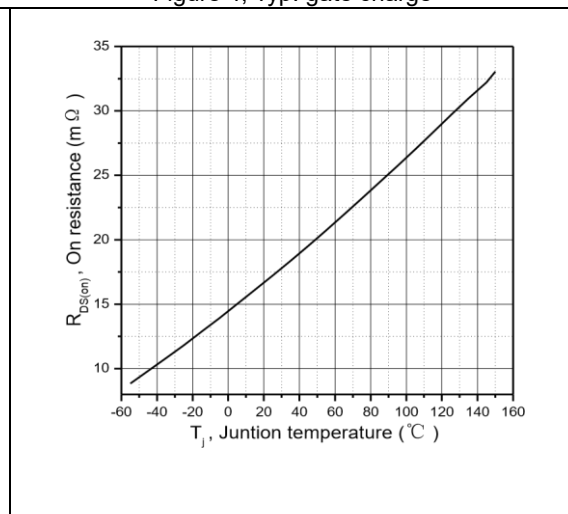


Figure 6, Drain-source on-state resistance

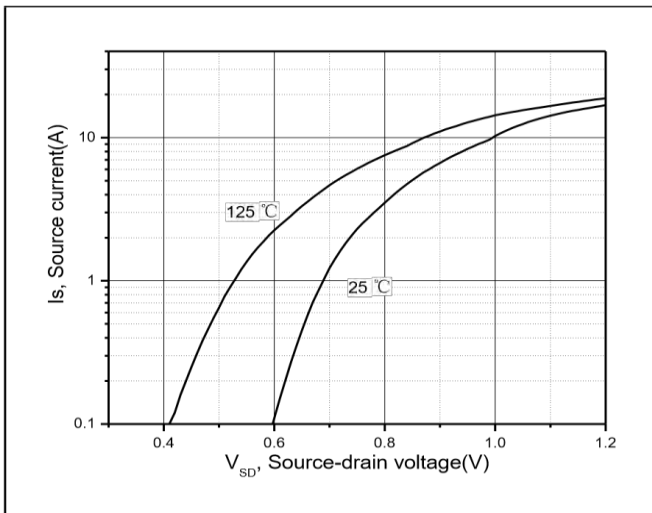


Figure 7, Forward characteristic of body diode

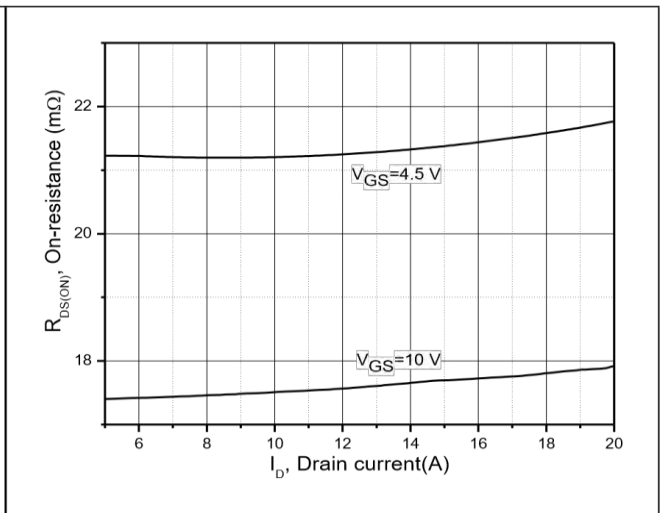


Figure 8, Drain-source on-state resistance

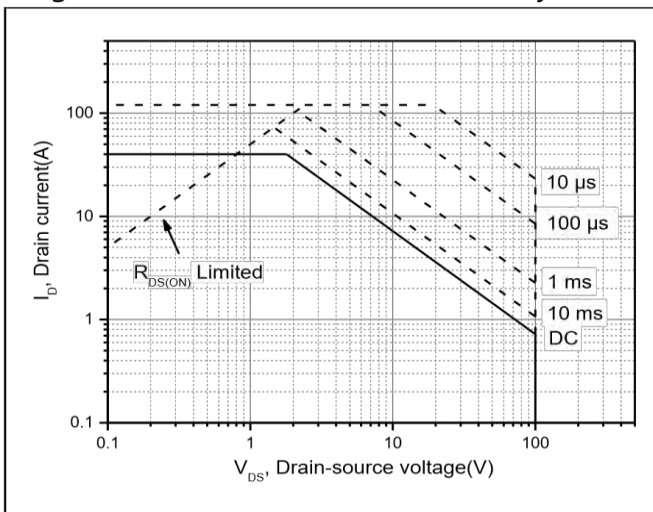


Figure 9, Safe operation area $T_C=25\text{ }^{\circ}\text{C}$

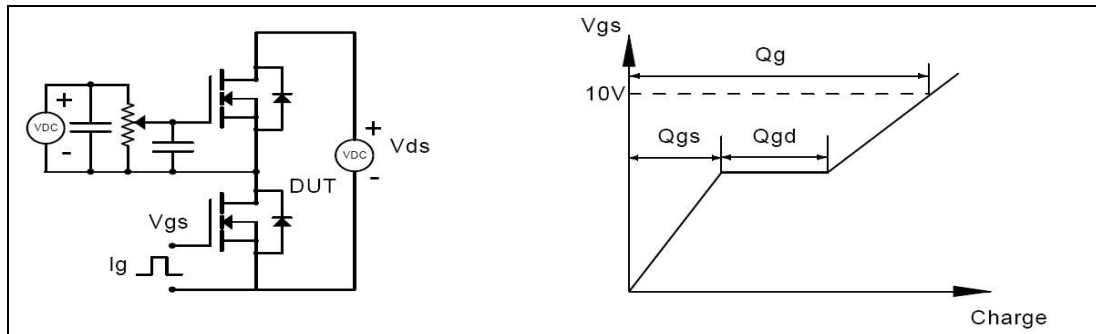


Figure 1, Gate charge test circuit & waveform

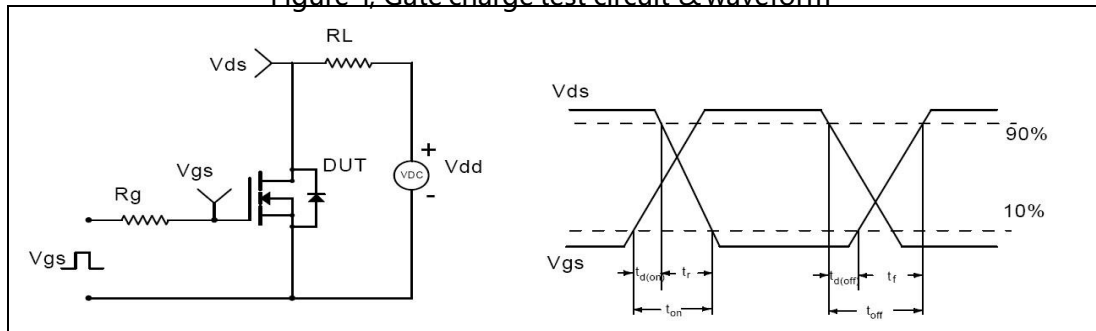


Figure 2, Switching time test circuit & waveforms

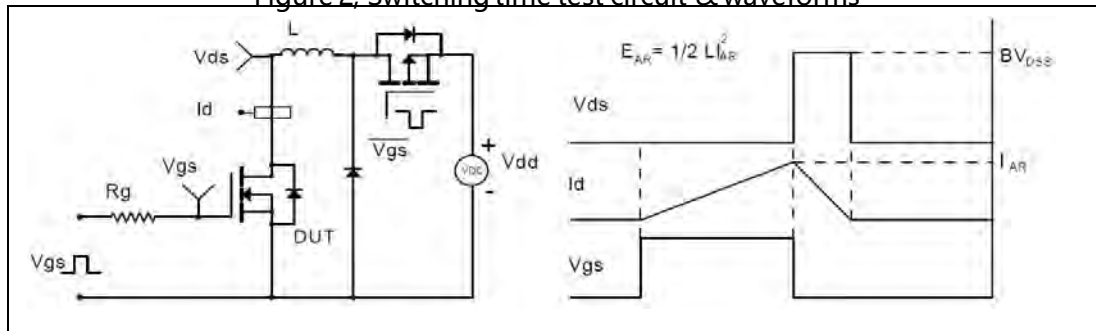


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

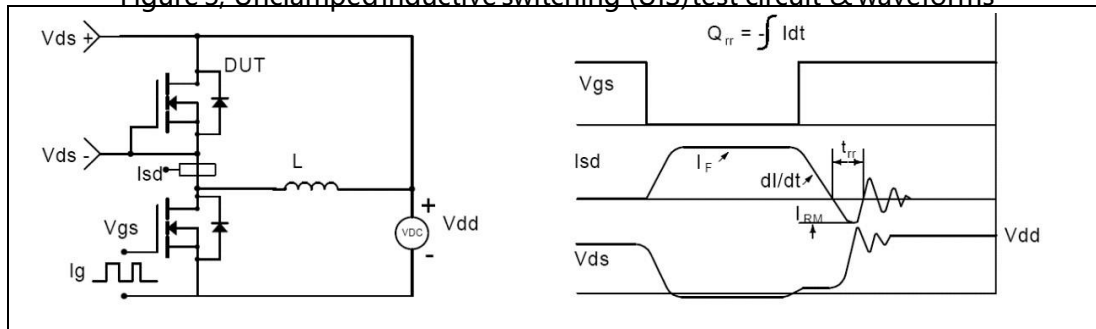
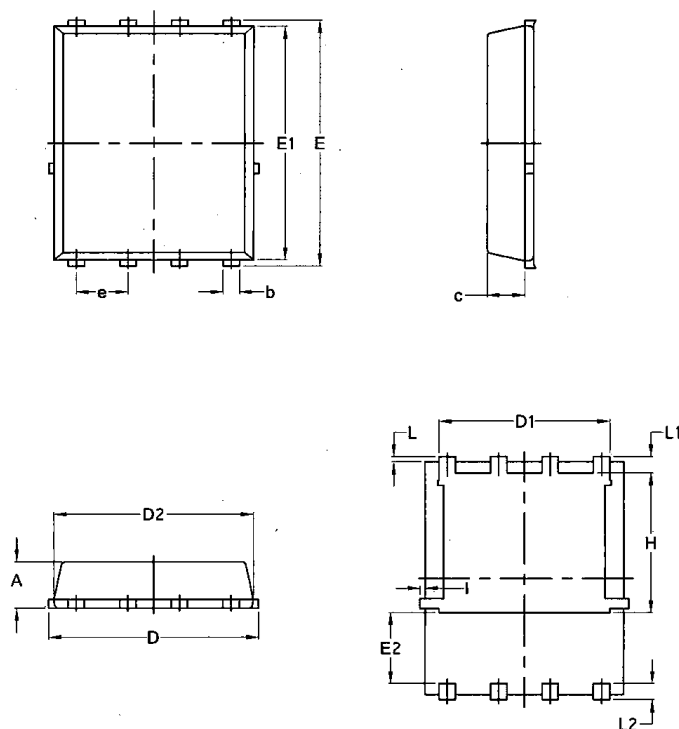


Figure 4, Diode reverse recovery test circuit & waveforms

Package Mechanical Data-DFN5*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070